Erratum to: The Effects of Composition and Microstructure on the Thermal Conductivity of Liquid-Phase-Sintered W-Cu

JOHN L. JOHNSON, SEONG JIN PARK, YOUNG-SAM KWON,
and RANDALL M. GERMAN

DOI: 10.1007/s11661-010-0312-5

© The Minerals, Metals & Materials Society and ASM International 2010

**Erratum to: METALLURGICAL AND MATERIALS
TRANSACTIONS A, Vol. 41A, No. 6, pp. 1564–1572
DOI 10.1007/s11661-010-0210-x**

FIGURE 11 is incorrect as it appears in the original article due to a typesetting error. The typesetter regrets the error. Following is the correct Figure 11:

Fig. 11—Effect of grain size on the thermal conductivity of pure, pore-free W-15Cu with a contiguity of 0.35 for different thermal boundary conductances, h . Experimental data from Table I and a previous study^[33] are given for comparison.

JOHN L. JOHNSON, R&D Director, is with ATI Engineered Products, Huntsville, AL 35806. Contact e-mail: John.Johnson@ATImetals.com SEONG JIN PARK, Assistant Professor, is with the Department of Mechanical Engineering, Pohang University of Science and Technology (POSTECH), Pohang, Gyungbuk, 790-784, S. Korea. YOUNG-SAM KWON, President, is with CetaTech, Inc., Sacheon, Gyungnam, 664-953, S. Korea. RANDALL M. GERMAN, Associate Dean, is with the College of Engineering, San Diego State University, San Diego, CA 92182-1326.

The online version of the original article can be found under doi: [10.1007/s11661-010-0210-x](https://doi.org/10.1007/s11661-010-0210-x).

Article published online May 14, 2010